Title (en)

MICROCIRCUIT SUBSTRATE AND METHOD OF MAKING SAME

Publication

EP 0149923 A3 19861210 (EN)

Application

EP 84309089 A 19841227

Priority

US 57308484 A 19840123

Abstract (en)

[origin: EP0149923A2] Individual ceramic substrates for electronic microcircuits are formed in an array having rectangular perforations (118) which define score lines (12) along which the array is broken to yield the individual substrates. The surfaces of the rectangular perforations are metallised and leads are attached thereto by thermocompression bonding after the array is broken. The rectangular perforations result in semi-rectangular openings around the periphery of the individual substrates. This eliminates tensile forces which cause cracking of the substrate during lead bonding.

IPC 1-7

H01L 21/48; H01L 23/48

IPC 8 full level

H01L 23/12 (2006.01); **H01L 21/48** (2006.01); **H01L 23/498** (2006.01); **H05K 3/40** (2006.01); H05K 1/09 (2006.01); H05K 3/00 (2006.01); H05K 3/32 (2006.01); H05K 3/42 (2006.01)

CPC (source: EP US)

H01L 21/4853 (2013.01 - EP US); **H01L 23/49805** (2013.01 - EP US); **H01L 24/97** (2013.01 - EP US); **H05K 3/403** (2013.01 - EP US); H01L 24/45 (2013.01 - EP US); H01L 2224/45124 (2013.01 - EP US); H01L 2224/45144 (2013.01 - EP US); H01L 2924/00014 (2013.01 - EP US); H01L 2924/01005 (2013.01 - EP US); H01L 2924/01006 (2013.01 - EP US); H01L 2924/01013 (2013.01 - EP US); H01L 2924/01029 (2013.01 - EP US); H01L 2924/01033 (2013.01 - EP US); H01L 2924/01079 (2013.01 - EP US); H01L 2924/01082 (2013.01 - EP US); H01L 2924/01322 (2013.01 - EP US); H01L 2924/14 (2013.01 - EP US); H01L 2924/15787 (2013.01 - EP US); H05K 1/092 (2013.01 - EP US); H05K 3/0052 (2013.01 - EP US); H05K 3/328 (2013.01 - EP US); H05K 3/4061 (2013.01 - EP US); H05K 3/42 (2013.01 - EP US); H05K 2201/09181 (2013.01 - EP US); H05K 2201/09854 (2013.01 - EP US); H05K 2201/10946 (2013.01 - EP US); Y10T 29/49121 (2015.01 - EP US); Y10T 29/49139 (2015.01 - EP US); Y10T 29/49142 (2015.01 - EP US); Y10T 29/49144 (2015.01 - EP US); Y10T 29/49147 (2015.01 - EP US); Y10T 29/49149 (2015.01 - EP US); Y10T 29/49165 (2015.01 - EP US); Y10T 156/1056 (2015.01 - EP US)

Citation (search report)

- [X] US 4271426 A 19810602 - HARGIS BILLY M
- [A] US 3926746 A 19751216 - HARGIS BILLY M

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Designated contracting state (EPC)

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EP 0149923 A2 19850731; **EP 0149923 A3 19861210**; JP S60227449 A 19851112; US 4572757 A 19860225

DOCDB simple family (application)

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